WHAT IS CLAIMED IS:

1. A solid electrolytic capacitor comprising:

an anode composed of a metal;

a dielectric layer composed of an oxide of said metal and formed on the surface of said anode; and

a metal layer formed on the surface of said dielectric layer.

2. The solid electrolytic capacitor according to Claim 1, wherein

said metal layer is composed of metal particles.

3. The solid electrolytic capacitor according to Claim 2, wherein

an average particle diameter of said metal particles is not larger than 0.05 μm.

4. The solid electrolytic capacitor according to Claim 2, wherein

said average particle diameter of said metal particles is not smaller than 0.01 μm.

5. The solid electrolytic capacitor according to Claim 2, wherein

said metal particles include at least one kind of metal selected from the group consisting of silver, gold, and platinum.

6. The solid electrolytic capacitor according to Claim 1, wherein

said metal layer includes a protective colloid.

7. The solid electrolytic capacitor according to Claim 1, wherein

said metal layer is composed of a metal plated layer.

8. The solid electrolytic capacitor according to Claim 1, wherein

said anode includes at least one kind of metal selected from the group consisting of tantalum, aluminum, niobium, and titanium.

9. A method of manufacturing a solid electrolytic capacitor including the steps of:

forming on the surface of an anode composed of a metal a dielectric layer composed of an oxide of said metal; and

forming a metal layer on said dielectric layer.

10. The method of manufacturing a solid electrolytic

capacitor according to Claim 9, wherein

said step of forming said metal layer includes the step of forming said metal layer by metal particles.

11. The method of manufacturing a solid electrolytic capacitor according to Claim 10, wherein

an average particle diameter of said metal particles is not larger than 0.05 μm.

12. The method of manufacturing a solid electrolytic capacitor according to Claim 10, wherein

said average particle diameter of said metal particles is not smaller than 0.01 μm.

13. The method of manufacturing a solid electrolytic capacitor according to Claim 10, wherein

said step of forming said metal layer includes the steps of:

applying a metal paste including said metal particles on said dielectric layer; and

drying said metal paste at a temperature of 150°C or higher after applying said metal paste.

14. The method of manufacturing a solid electrolytic capacitor according to Claim 10, wherein

said step of forming said metal layer including the steps of:

preparing a metal paste by mixing said metal particles and a protective colloid in an organic solvent; and

applying said metal paste on the surface of said dielectric layer.

15. The method of manufacturing a solid electrolytic capacitor according to Claim 9, wherein

said step of forming said metal layer includes the step of forming said metal layer by metal plating.